

APPLICATION DATA SHEET

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Application Information:

Title of Invention:	Method And Device For Reflow Soldering With Volume Flow Control
Application Type:	regular, utility
Attorney Docket Number:	2380.0030000

Botanic Information:

Publication Information:**Suggested Figure for Publication -****Suggested Classification -****Suggested Technology Center -****Total Number of Drawing Sheets - 3*****Representative Information:***

practitioner(s) at Customer Number:

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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of US application number PCT/EP2004/012262, filed 2004-10-29, now pending.

Foreign Priority Information:**Doc.No:**10350699.3; **Country** - DE; **Date:** 2003-10-30 us-priority-claimed***Assignee Information:***Assignee 1:**Organization Name:** Rehm Anlagenbau GmbH**Address-1 of Mailing Address:** Leinenstrasse 7**Address-2 of Mailing Address:****City of Mailing Address:** Blaubeuren-Seissen**State of Mailing Address:****Postal Code of Mailing Address:** 89143**Country of Mailing Address:** DE**Phone:****Fax:****E-mail:**

